

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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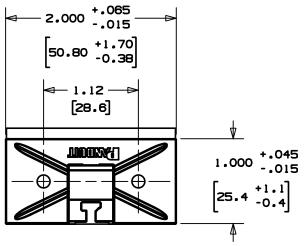
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







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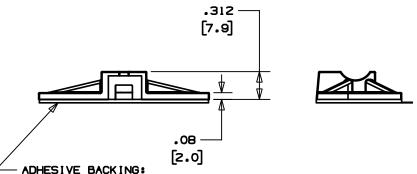
PANDUIT PART NO. *	REC'M FASTENER	USE WITH THESE CABLE TIES **	WEIGHT bs 100 (g) pcs
SMS-A		S = STANDARD	0.81 (371)
SMS-S6	#6 F.H.C.S or B.H.C.S		0.74 (335)

TO APPLY ADHESIVE MOUNT:

- 1. REMOVE PROTECTIVE LINER.
 2. PLACE IN DESIRED LOCATION.
- 3. APPLY PRESSURE TO TOP SURFACE OF MOUNT.

NOTES:

1. SEE CURRENT PRICE SHEET FOR PART NUMBER SUFFIX DESIGNATION FOR PACKAGE SIZE AND COLOR.



ADHESIVE BACKING:
PRESSURE SENSITIVE FOAM TAPE 0.040" (1.0)
THICK WITH PROTECTIVE LINER. MOUNT IS DESIGNED
TO SUPPORT 116. (454g) MAX. WEIGHT ON A
CLEAN DRY, SMOOTH, GREASE-FREE SURFACE.

1/28/04

DATE

REV

JAD

BY

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NO WARRANTY, EXPRESSED, OR IMPLIED, IS MADE BY PANDUIT WITH RESPECT TO ADHESIVE BOND PERFORMANCE. AMONG OTHER THINGS, THE CONDITIONS UNDER WHICH THESE MOUNTS MAY BE APPLIED AND/OR THE SURFACE TO WHICH THEY MAY BE APPLIED ARE BEYOND PANDUIT'S CONTROL.

GB0239LA

ECN - R

R

CUST

SUP

INITIAL RELEASE

DESCRIPTION





DIMENSIONS IN BRACKETS ARE METRIC [mm]

CAD FILENWEZLAYERS

G00239LA_PB_SMS_00

PANDUIT

TINLEY PARK, ILLINOIS

SNAP IN MOUNT (SMS-A, -S6)

UNLESS OTHERWISE SPECIFIED, DIMENSIONAL TOLERANCES ARE:

ALL DIMENSIONS ARE GIVEN

(.X) ±0.05(1.31(.XXX) ±0.010(0.25) (.XX) ±0.02(0.5) ANGLES ±5°

ABS

IN INCHES, THIRD ANGLE PROJECTION.

MAT*Ls

DRAFING NO.

DATE 1/28/04 CHC'D

GB0239LA

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